




## Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-09-15
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

<b>Uncertainty Statement</b>	
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<b>Legal Statement</b>	
Supplier Acceptance *	<div> <div>true</div> <div>Legal Declaration *</div> <div>Standard</div> </div>
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HD6R*UY29ABA	A	BO2A	2014-09-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	54.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	5 - 4.4 - 0.9	14	J bend	
Comment	TSSOP 14 BODY 4.4 PITCH 0.65; MD valid for CP:TSX634AIPT, TSX634IPT.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HD6R*UY29ABA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2.146	mg	supplier	die	Silicon (Si)	7440-21-3		2.113	mg	984623	39130
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.01	mg	4660	185
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.001	mg	466	19
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1864	74
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.012	mg	5592	222
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.006	mg	2796	111
Leadframe	Copper & its alloys	23.817	mg	supplier	alloy	Copper (Cu)	7440-50-8		22.897	mg	961372	424019
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.714	mg	29979	13222
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.036	mg	1512	667
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.155	mg	6508	2870
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.014	mg	588	259
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	42	19
Die attach	Other Organic Materials	0.628	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.477	mg	759554	8833
Die attach				supplier	glue or tape	2,6-Diglycidylphenyl allyl ether	13561-08-5		0.063	mg	100318	1167
Die attach				supplier	glue or tape	1,4-bis (2,3-epoxypropoxy) butane	2425-79-8		0.025	mg	39809	463
Die attach				supplier	glue or tape	2,6-Diglycidyl phenyl allyl ether	GE 417-470-1		0.038	mg	60510	704
Die attach				supplier	glue or tape	Polyoxypropylenediamine	9046-10-0		0.025	mg	39809	463
Bonding wire	Other inorganic materials	0.207		supplier	wire	Gold (Au)	7440-57-5		0.207	mg	1000000	3833
encapsulation	Other Organic Materials	27.202	mg	supplier	mold compound	Silica, vitreous	60676-86-0		24.127	mg	886957	446796
encapsulation				supplier	mold compound	epoxy resin	Proprietary		2.177	mg	80031	40315
encapsulation				supplier	mold compound	Phenol resin	Proprietary		0.816	mg	29998	15111
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.082	mg	3014	1519